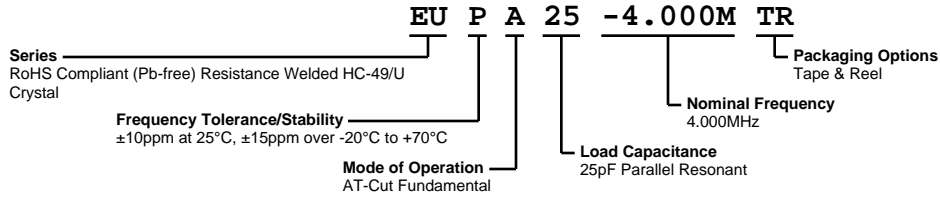


EUPA25-4.000M TR



ECLIPTEK
CORPORATION



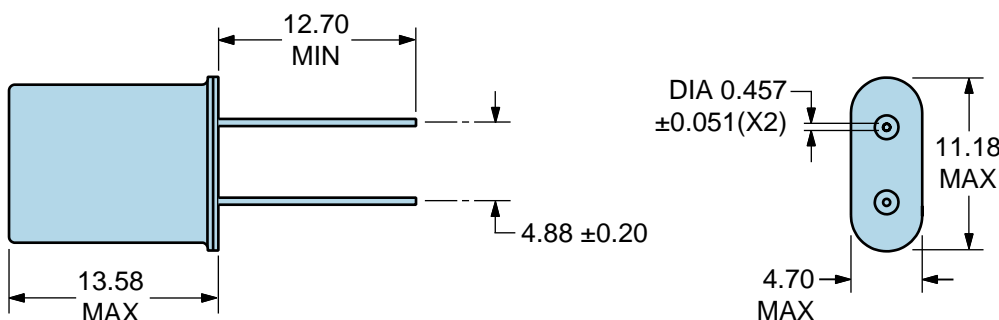
ELECTRICAL SPECIFICATIONS

Nominal Frequency	4.000MHz
Frequency Tolerance/Stability	$\pm 10\text{ppm}$ at 25°C, $\pm 15\text{ppm}$ over -20°C to +70°C
Aging at 25°C	$\pm 5\text{ppm}/\text{year}$ Maximum
Load Capacitance	25pF Parallel Resonant
Shunt Capacitance (C0)	7pF Maximum
Equivalent Series Resistance	100 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	2mWatts Maximum
Storage Temperature Range	-40°C to +125°C
Insulation Resistance	500 Megaohms Minimum at 100Vdc

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Lead Integrity	MIL-STD-883, Method 2004
Lead Termination	Sn 2 μm - 6 μm
Mechanical Shock	MIL-STD-202, Method 213, Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007, Condition A

MECHANICAL DIMENSIONS (all dimensions in millimeters)

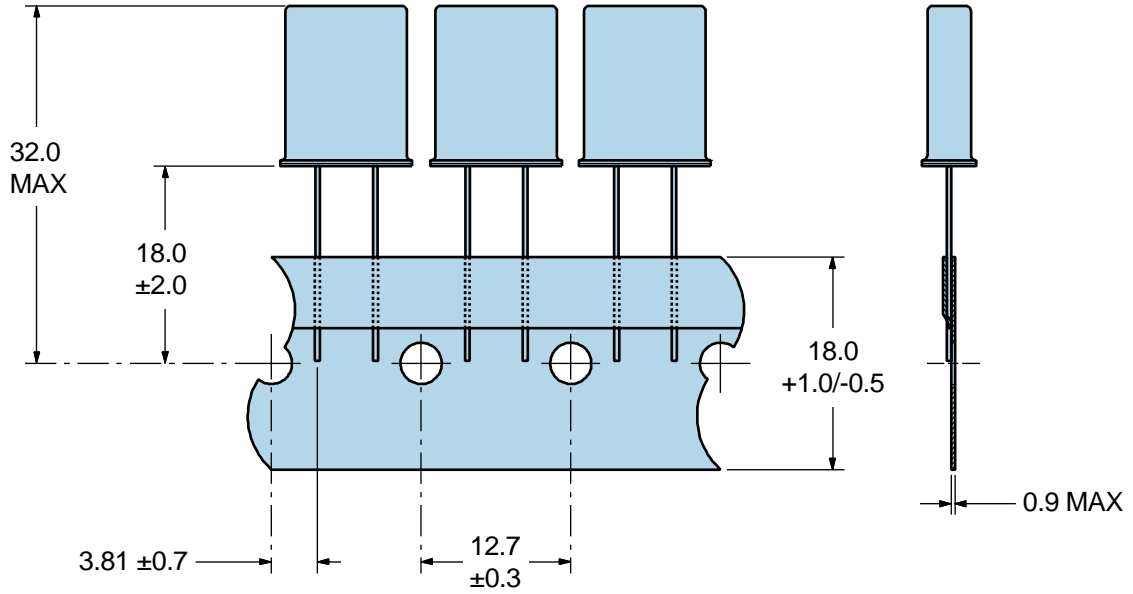


LINE	MARKING
1	ECLIPTEK
2	E4.000M <i>E=Configuration Designator</i>
3	XX <i>XX=Ecliptek Manufacturing Code</i>

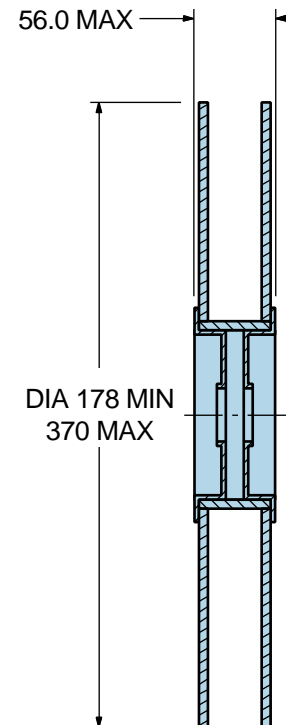
EUPA25-4.000M TR

Tape & Reel Dimensions

Quantity Per Reel: 1,000 units



*Compliant to EIA 468B



Recommended Solder Reflow Methods



High Temperature Solder Bath (Wave Solder)

$T_S\ MAX$ to T_L (Ramp-up Rate) $3^\circ C/second$ Maximum

Preheat

- Temperature Minimum ($T_S\ MIN$) $150^\circ C$
- Temperature Typical ($T_S\ TYP$) $175^\circ C$
- Temperature Maximum ($T_S\ MAX$) $200^\circ C$
- Time ($t_s\ MIN$) $60 - 180$ Seconds

Ramp-up Rate (T_L to T_P) $3^\circ C/second$ Maximum

Time Maintained Above:

- Temperature (T_L) $217^\circ C$
- Time (t_L) $60 - 150$ Seconds

Peak Temperature (T_P) $260^\circ C$ Maximum for 10 Seconds Maximum

Target Peak Temperature (T_P Target) $250^\circ C +0/-5^\circ C$

Time within $5^\circ C$ of actual peak (t_p) $20 - 40$ seconds

Ramp-down Rate $6^\circ C/second$ Maximum

Time $25^\circ C$ to Peak Temperature (t) 8 minutes Maximum

Moisture Sensitivity Level Level 1

Recommended Solder Reflow Methods



Low Temperature Solder Bath (Wave Solder)

T_s MAX to T_L (Ramp-up Rate)	5°C/second Maximum
Preheat	
- Temperature Minimum (T _s MIN)	N/A
- Temperature Typical (T _s TYP)	150°C
- Temperature Maximum (T _s MAX)	N/A
- Time (t _s MIN)	30 - 60 Seconds
Ramp-up Rate (T_L to T_P)	5°C/second Maximum
Time Maintained Above:	
- Temperature (T _L)	150°C
- Time (t _L)	200 Seconds Maximum
Peak Temperature (T_P)	245°C Maximum
Target Peak Temperature (T_P Target)	245°C Maximum 1 Time / 235°C Maximum 2 Times
Time within 5°C of actual peak (t_p)	5 seconds Maximum 1 Time / 15 seconds Maximum 2 Times
Ramp-down Rate	5°C/second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.